

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|---|---|------------------|---------|------------------|
| S1 | 15637 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:21 |
| S2 | 1967 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:21 |
| S3 | 586 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:22 |
| S4 | 341 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:22 |
| S5 | 109 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:22 |
| S6 | 69 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:22 |
| S7 | 53 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 and lead | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:23 |
| S8 | 43 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 and lead and electrode | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:23 |

| | | | | | | |
|-----|----|--|---|----|-----|------------------|
| S9 | 41 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 and lead and electrode and solder | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:24 |
| S10 | 0 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 and lead and electrode and solder and (438/585.ccls.) | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:23 |